

# 12-Bit, 4-Channel Serial Output Sampling ANALOG-TO-DIGITAL CONVERTER

## FEATURES

- SINGLE SUPPLY: 2.7V to 5V
- 4-CHANNEL SINGLE-ENDED OR 2-CHANNEL DIFFERENTIAL INPUT
- UP TO 200kHz CONVERSION RATE
- $\pm 1$ LSB MAX INL AND DNL
- NO MISSING CODES
- 72dB SINAD
- SERIAL INTERFACE
- DIP-16 OR SSOP-16 PACKAGE
- ALTERNATE SOURCE FOR MAX1247
- ADS7841ES: +125°C Version

## APPLICATIONS

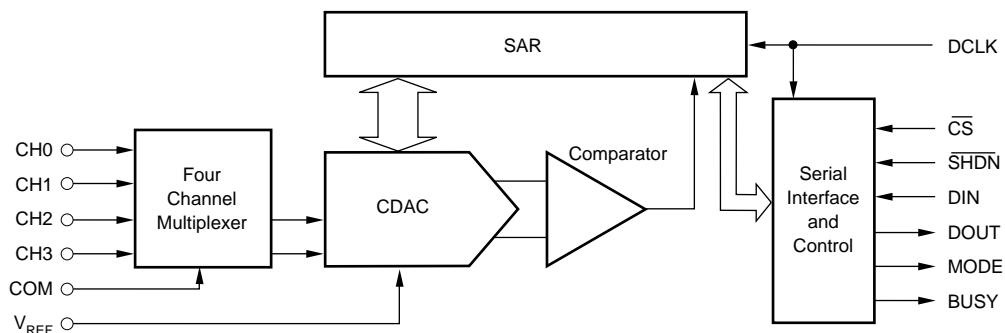
- DATA ACQUISITION
- TEST AND MEASUREMENT
- INDUSTRIAL PROCESS CONTROL
- PERSONAL DIGITAL ASSISTANTS
- BATTERY-POWERED SYSTEMS

## DESCRIPTION

The ADS7841 is a 4-channel, 12-bit sampling Analog-to-Digital Converter (ADC) with a synchronous serial interface. The resolution is programmable to either 8 bits or 12 bits. Typical power dissipation is 2mW at a 200kHz throughput rate and a +5V supply. The reference voltage ( $V_{REF}$ ) can be varied between 100mV and  $V_{CC}$ , providing a corresponding input voltage range of 0V to  $V_{REF}$ . The device includes a shutdown mode which reduces power dissipation to under 15 $\mu$ W. The ADS7841 is tested down to 2.7V operation.

Low power, high speed, and on-board multiplexer make the ADS7841 ideal for battery-operated systems such as personal digital assistants, portable multi-channel data loggers, and measurement equipment. The serial interface also provides low-cost isolation for remote data acquisition. The ADS7841 is available in a DIP-16 or a SSOP-16 package and is specified over the  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}^{(1)}$  temperature range.

NOTE: (1) ES grade only.



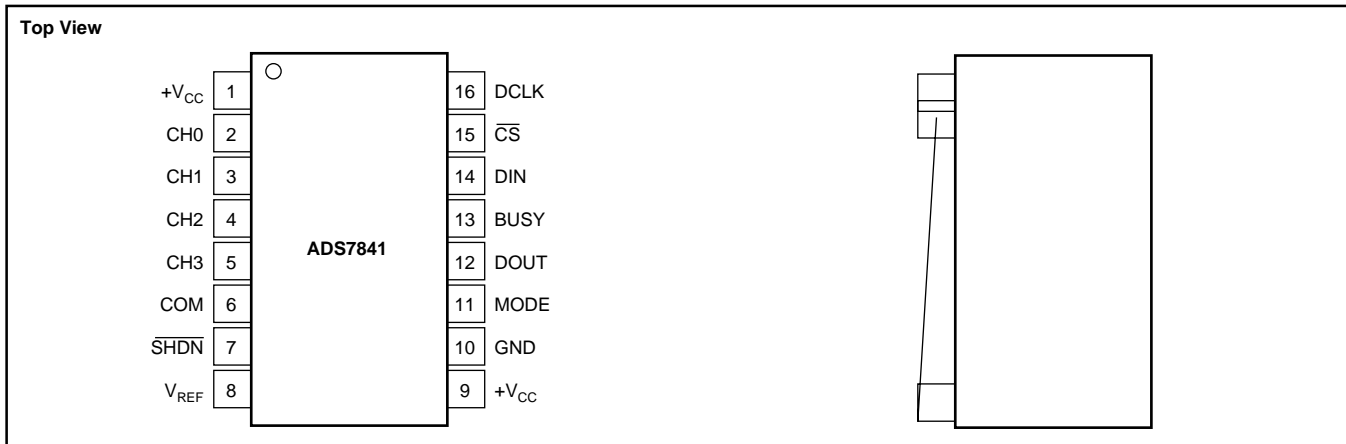
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

## PACKAGE/ORDERING INFORMATION

PRODUCT	MINIMUM RELATIVE ACCURACY (LSB)	MAXIMUM GAIN ERROR (LSB)	SPECIFICATION TEMPERATURE RANGE	PACKAGE	PACKAGE DESIGNATOR	PACKAGE DRAWING NUMBER	ORDERING NUMBER <sup>(1)</sup>	TRANSPORT MEDIA
ADS7841E	±2	±4	-40°C to +85°C	SSOP-16	DBQ	322	ADS7841E	Rails
"	"	"	"	"	"	"	ADS7841E/2K5	Tape and Reel
ADS7841P	±2	"	-40°C to +85°C	DIP-16	N	180	ADS7841P	Rails
ADS7841EB	±1	±3	-40°C to +85°C	SSOP-16	DBQ	322	ADS7841EB	Rails
"	"	"	"	"	"	"	ADS7841EB/2K5	Tape and Reel
ADS7841PB	±1	"	-40°C to +85°C	DIP-16	N	180	ADS7841PB	Rails
ADS7841ES	±2	±4	-40°C to +125°C	SSOP-16	DBQ	322	ADS7841ES/2K5	Tape and Reel

NOTES: (1) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K5 indicates 2500 devices per reel). Ordering 2500 pieces of "ADS7841E/2K5" will get a single 2500-piece Tape and Reel.

## PIN CONFIGURATIONS



# ELECTRICAL CHARACTERISTICS: +5V

At  $T_A = T_{MIN}$  to  $T_{MAX}$ ,  $+V_{CC} = +5V$ ,  $V_{REF} = +5V$ ,  $f_{SAMPLE} = 200kHz$ , and  $f_{CLK} = 16 \cdot f_{SAMPLE} = 3.2MHz$ , unless otherwise noted.

PARAMETER	CONDITIONS	ADS7841E, P			ADS7841EB, PB			ADS7841ES			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
<b>ANALOG INPUT</b>											
Full-Scale Input Span	Positive Input - Negative Input	0		$V_{REF}$	*		*	*		*	V
Absolute Input Range	Positive Input	-0.2		$+V_{CC} + 0.2$	*		*	*		*	V
	Negative Input	-0.2		+1.25	*		*	*		*	V
Capacitance			25			*			*		pF
Leakage Current				200			200			200	nA
<b>SYSTEM PERFORMANCE</b>											
Resolution		12	12		12	*		11	*		Bits
No Missing Codes											Bits
Integral Linearity Error				$\pm 2$			$\pm 1$			2	LSB <sup>(1)</sup>
Differential Linearity Error			$\pm 0.8$			$\pm 0.5$	$\pm 1$		$\pm 0.8$		LSB
Offset Error				$\pm 3$			*			*	LSB
Offset Error Match			0.15	1.0		*	*		*	*	LSB
Gain Error				$\pm 4$			$\pm 3$			$\pm 4$	LSB
Gain Error Match			0.1	1.0		*	*		*	*	LSB
Noise			30			*			*		$\mu V_{rms}$
Power-Supply Rejection			70			*			*		dB
<b>SAMPLING DYNAMICS</b>											
Conversion Time				12			*			*	Clk Cycles
Acquisition Time		3			*			*			Clk Cycles
Throughput Rate				200			*			*	kHz
Multiplexer Settling Time			500			*			*		ns
Aperture Delay			30			*			*		ns
Aperture Jitter			100			*			*		ps
<b>DYNAMIC CHARACTERISTICS</b>											
Total Harmonic Distortion <sup>(2)</sup>	$V_{IN} = 5Vp-p$ at 10kHz		-78	-72		-80	-76		-78	-72	dB
Signal-to-(Noise + Distortion)	$V_{IN} = 5Vp-p$ at 10kHz	68	71		70	72		68	71		dB
Spurious-Free Dynamic Range	$V_{IN} = 5Vp-p$ at 10kHz		72	79		76	81		72	79	dB
Channel-to-Channel Isolation	$V_{IN} = 5Vp-p$ at 50kHz			120		*				120	dB
<b>REFERENCE INPUT</b>											
Range		0.1		$+V_{CC}$	*		*	*		*	V
Resistance	DCLK Static		5			*	*		*	*	G $\Omega$
Input Current	$f_{SAMPLE} = 12.5kHz$ DCLK Static		40	100		*	*		*	*	$\mu A$
			2.5			*	*		*	*	$\mu A$
			0.001	3		*	*		*	*	$\mu A$
<b>DIGITAL INPUT/OUTPUT</b>											
Logic Family			CMOS			*			*		
Logic Levels											
$V_{IH}$	$ I_{IH}  \leq +5\mu A$	3.0		5.5	*		*	*		*	V
$V_{IL}$	$ I_{IL}  \leq +5\mu A$	-0.3		+0.8	*		*	*		*	V
$V_{OH}$	$I_{OH} = -250\mu A$	3.5			*		*	*		*	V
$V_{OL}$	$I_{OL} = 250\mu A$			0.4			*			*	V
Data Format				Straight Binary		*			*		
<b>PWR SUPPLY REQUIREMENTS</b>											
$+V_{CC}$	Specified Performance	4.75		5.25	*		*	*		*	V
Quiescent Current	$f_{SAMPLE} = 12.5kHz$		550	900			*		*	*	$\mu A$
	Power-Down Mode <sup>(3)</sup> , $\overline{CS} = +V_{CC}$		300			*			*	*	$\mu A$
Power Dissipation				3			*		*	*	$\mu A$
				4.5			*		*	*	mW
<b>TEMPERATURE RANGE</b>											
Specified Performance		-40		+85	*		*	*		+125	$^{\circ}C$

\* Same specifications as ADS7841E, P.

NOTE: (1) LSB means Least Significant Bit. With  $V_{REF}$  equal to +5.0V, one LSB is 1.22mV. (2) First five harmonics of the test frequency. (3) Auto power-down mode (PD1 = PD0 = 0) active or SHDN = GND.

# ELECTRICAL CHARACTERISTICS: +2.7V

At  $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $+V_{CC} = +2.7\text{V}$ ,  $V_{REF} = +2.5\text{V}$ ,  $f_{SAMPLE} = 125\text{kHz}$ , and  $f_{CLK} = 16 \cdot f_{SAMPLE} = 2\text{MHz}$ , unless otherwise noted.

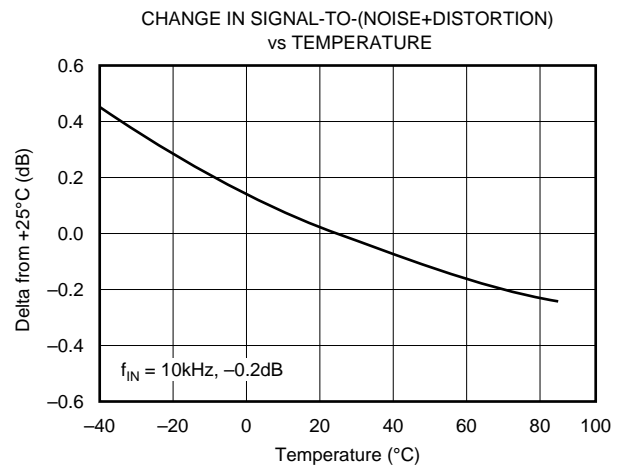
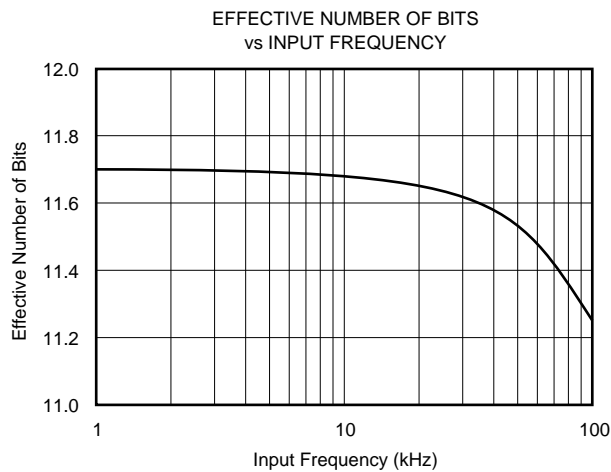
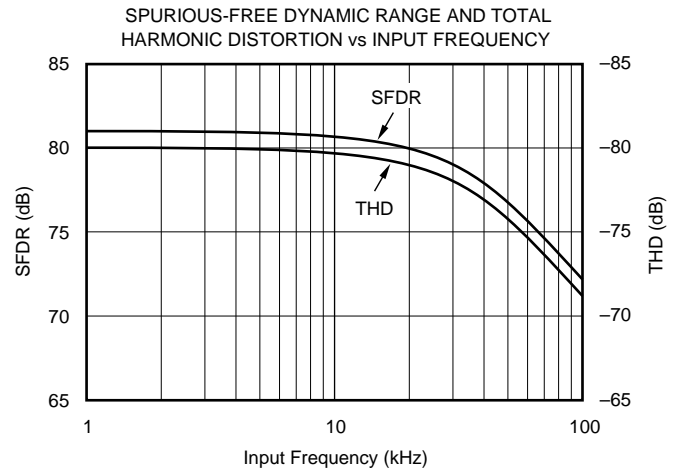
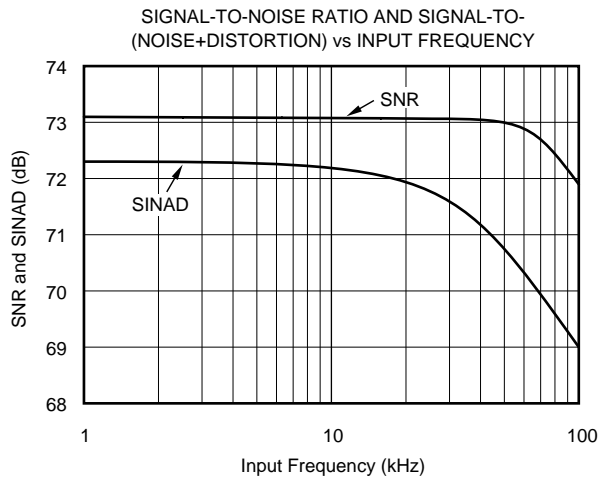
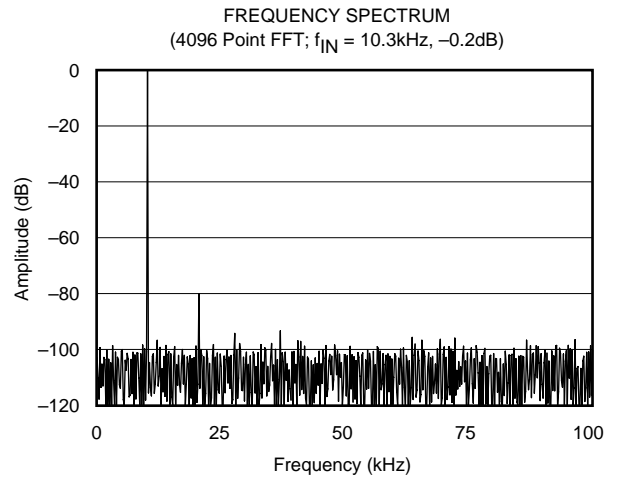
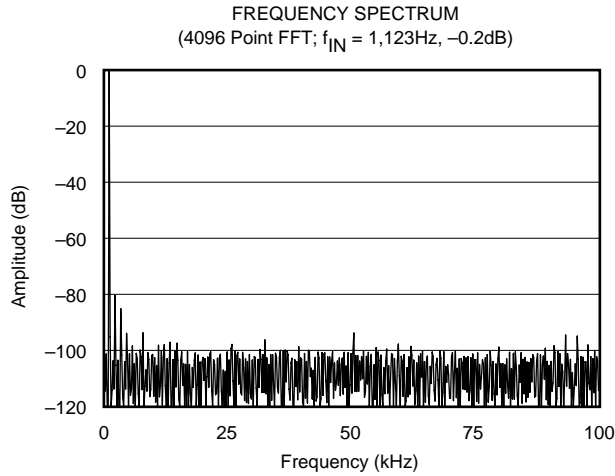
PARAMETER	CONDITIONS	ADS7841E, P			ADS7841EB, PB			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>ANALOG INPUT</b>								
Full-Scale Input Span	Positive Input - Negative Input	0		$V_{REF}$	*		*	V
Absolute Input Range	Positive Input	-0.2		$+V_{CC} + 0.2$	*		*	V
	Negative Input	-0.2		$+0.2$	*		*	V
Capacitance			25			*		pF
Leakage Current			$\pm 1$			*		$\mu\text{A}$
<b>SYSTEM PERFORMANCE</b>								
Resolution			12		12	*		Bits
No Missing Codes		12			12			Bits
Integral Linearity Error				$\pm 2$			$\pm 1$	LSB <sup>(1)</sup>
Differential Linearity Error			$\pm 0.8$			$\pm 0.5$	$\pm 1$	LSB
Offset Error				$\pm 3$			*	LSB
Offset Error Match			0.15	1.0		*	*	LSB
Gain Error				$\pm 4$			$\pm 3$	LSB
Gain Error Match			0.1	1.0		*	*	LSB
Noise			30			*		$\mu\text{V}_{\text{rms}}$
Power-Supply Rejection			70			*		dB
<b>SAMPLING DYNAMICS</b>								
Conversion Time				12			*	Clk Cycles
Acquisition Time		3			*			Clk Cycles
Throughput Rate				125			*	kHz
Multiplexer Settling Time			500			*		ns
Aperture Delay			30			*		ns
Aperture Jitter			100			*		ps
<b>DYNAMIC CHARACTERISTICS</b>								
Total Harmonic Distortion <sup>(2)</sup>	$V_{IN} = 2.5\text{V}_{\text{p-p}}$ at 10kHz		-77	-72		-79	-76	dB
Signal-to-(Noise + Distortion)	$V_{IN} = 2.5\text{V}_{\text{p-p}}$ at 10kHz	68	71		70	72		dB
Spurious-Free Dynamic Range	$V_{IN} = 2.5\text{V}_{\text{p-p}}$ at 10kHz	72	78		76	80		dB
Channel-to-Channel Isolation	$V_{IN} = 2.5\text{V}_{\text{p-p}}$ at 50kHz		100			*		dB
<b>REFERENCE INPUT</b>								
Range	DCLK Static	0.1		$+V_{CC}$	*		*	V
Resistance			5			*	*	$\text{G}\Omega$
Input Current	$f_{SAMPLE} = 12.5\text{kHz}$		13	40		*	*	$\mu\text{A}$
	DCLK Static		2.5	3		*	*	$\mu\text{A}$
			0.001			*	*	$\mu\text{A}$
<b>DIGITAL INPUT/OUTPUT</b>								
Logic Family			CMOS			*		
Logic Levels								
$V_{IH}$	$ I_{IH}  \leq +5\mu\text{A}$	$+V_{CC} \cdot 0.7$		5.5	*		*	V
$V_{IL}$	$ I_{IL}  \leq +5\mu\text{A}$	-0.3		+0.8	*		*	V
$V_{OH}$	$I_{OH} = -250\mu\text{A}$	$+V_{CC} \cdot 0.8$			*		*	V
$V_{OL}$	$I_{OL} = 250\mu\text{A}$			0.4			*	V
Data Format			Straight Binary			*		
<b>POWER SUPPLY REQUIREMENTS</b>								
$+V_{CC}$	Specified Performance	2.7		3.6	*		*	V
Quiescent Current			280	650		*	*	$\mu\text{A}$
	$f_{SAMPLE} = 12.5\text{kHz}$		220			*	*	$\mu\text{A}$
	Power-Down Mode <sup>(3)</sup> , $\overline{CS} = +V_{CC}$			3			*	$\mu\text{A}$
Power Dissipation				1.8			*	mW
<b>TEMPERATURE RANGE</b>								
Specified Performance		-40		+85	*		*	$^{\circ}\text{C}$

\* Same specifications as ADS7841E, P.

NOTE: (1) LSB means Least Significant Bit. With  $V_{REF}$  equal to +2.5V, one LSB is 610mV. (2) First five harmonics of the test frequency. (3) Auto power-down mode (PD1 = PD0 = 0) active or  $\overline{SHDN} = \text{GND}$ .

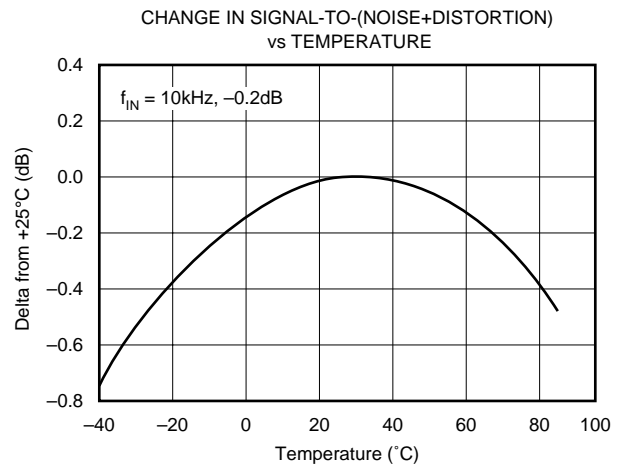
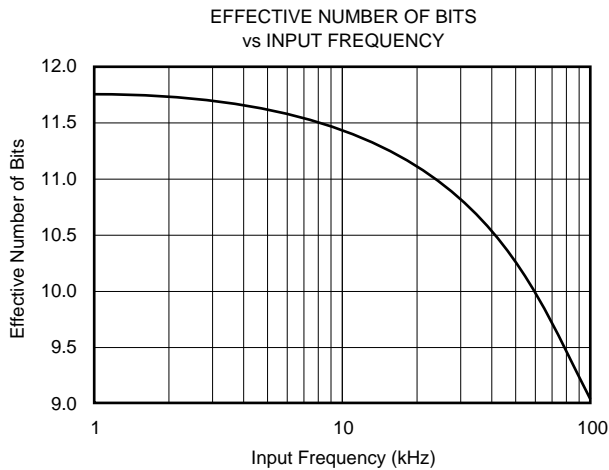
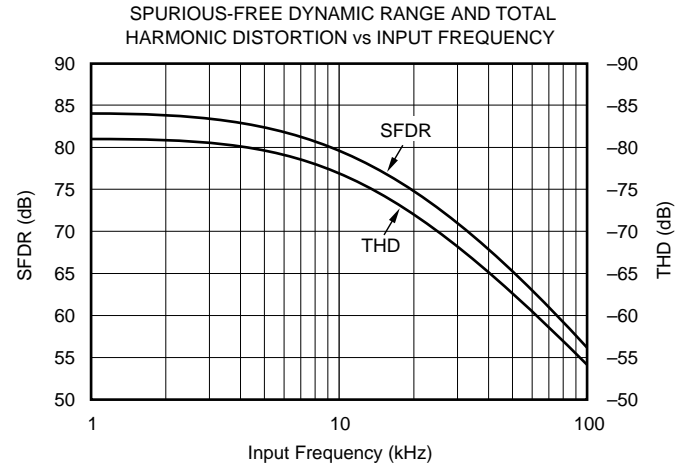
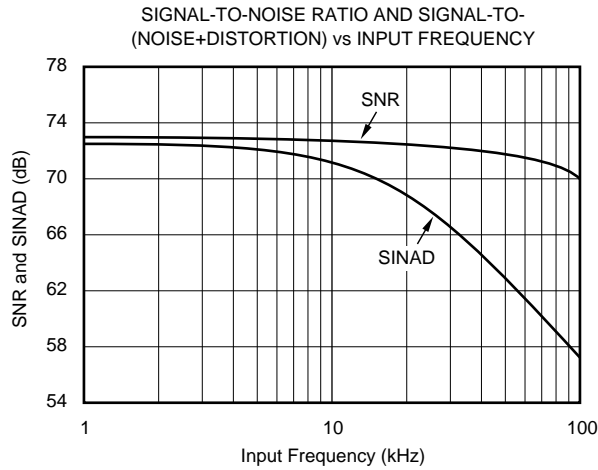
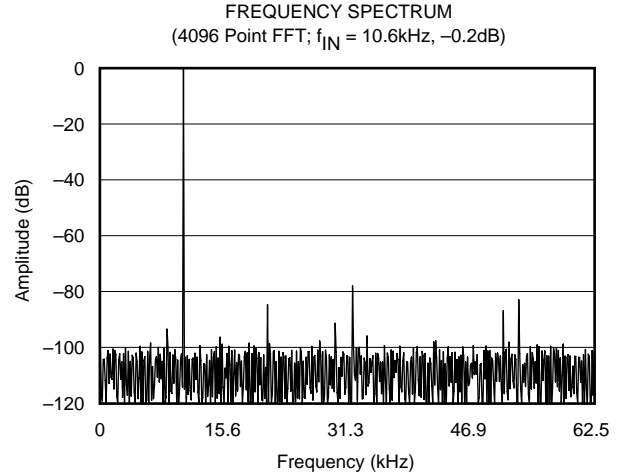
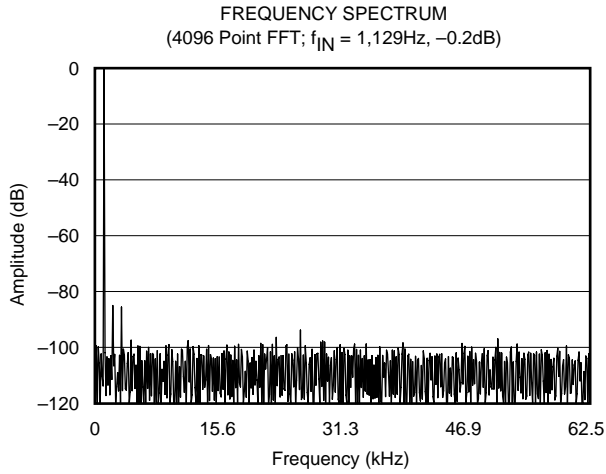
# TYPICAL CHARACTERISTICS: +5V

At  $T_A = +25^\circ\text{C}$ ,  $V_{CC} = +5\text{V}$ ,  $V_{REF} = +5\text{V}$ ,  $f_{\text{SAMPLE}} = 200\text{kHz}$ , and  $f_{\text{CLK}} = 16 \cdot f_{\text{SAMPLE}} = 3.2\text{MHz}$ , unless otherwise noted.



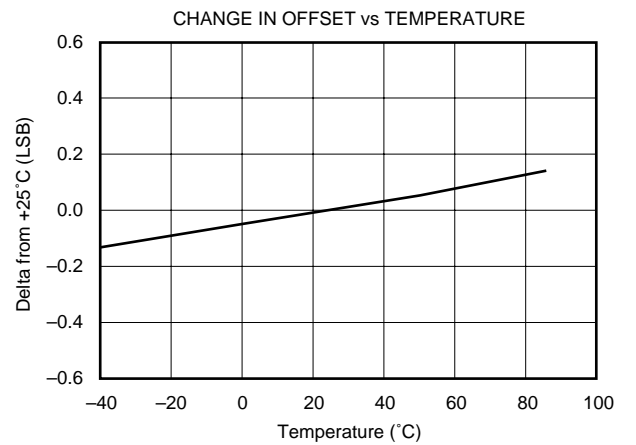
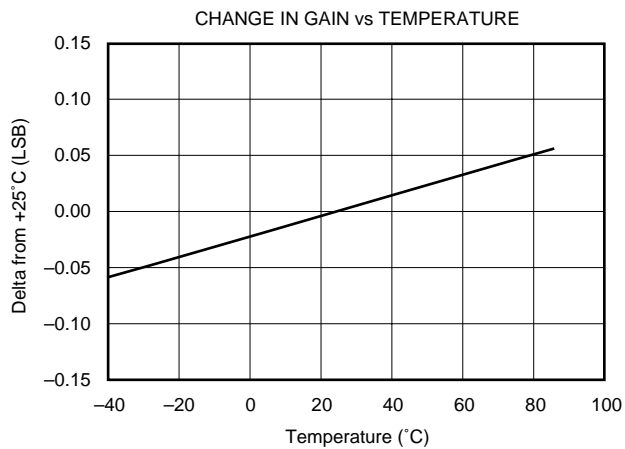
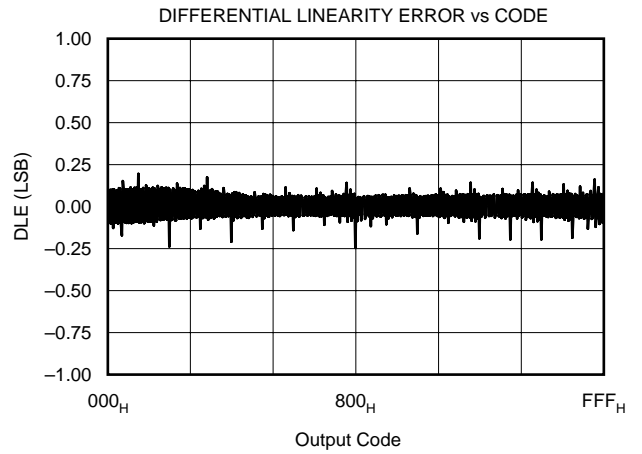
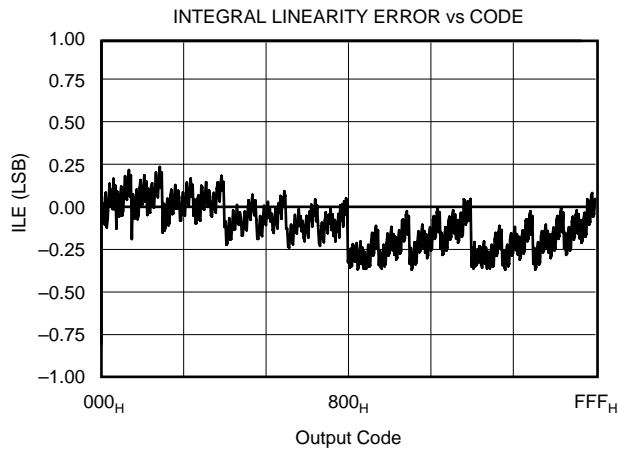
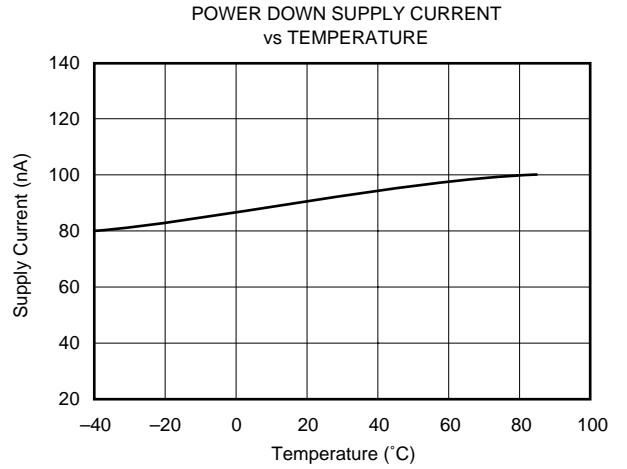
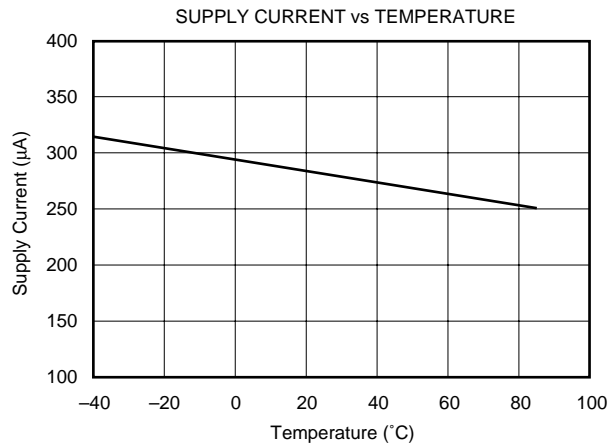
# TYPICAL CHARACTERISTICS: +2.7V

At  $T_A = +25^\circ\text{C}$ ,  $+V_{CC} = +2.7\text{V}$ ,  $V_{REF} = +2.5\text{V}$ ,  $f_{\text{SAMPLE}} = 125\text{kHz}$ , and  $f_{\text{CLK}} = 16 \cdot f_{\text{SAMPLE}} = 2\text{MHz}$ , unless otherwise noted.



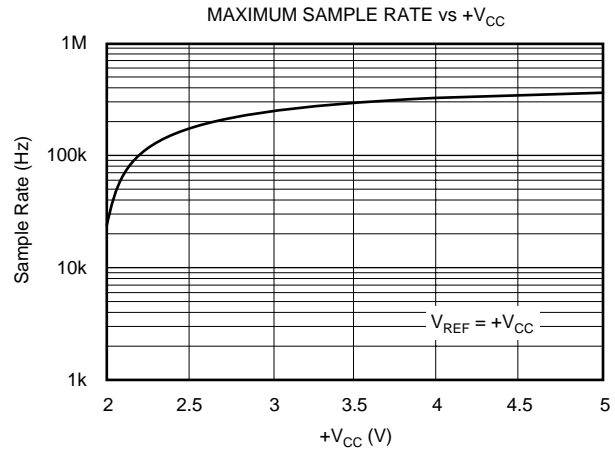
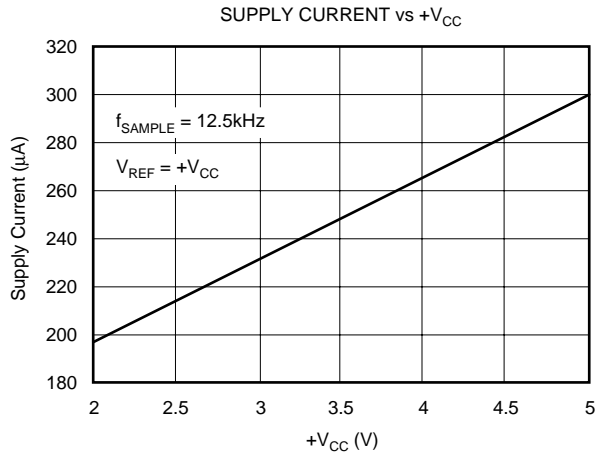
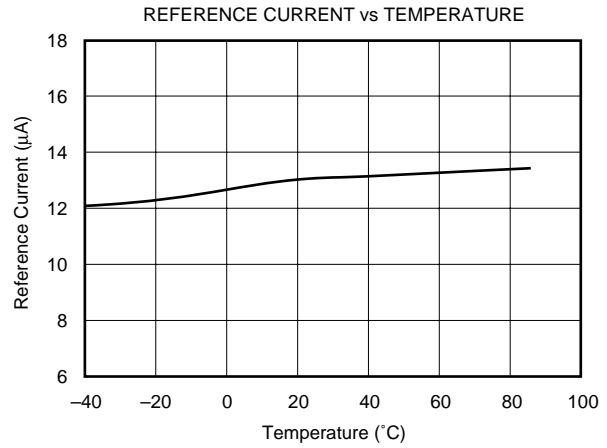
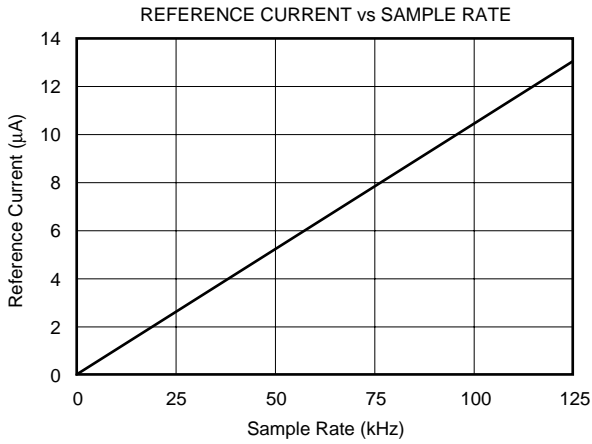
# TYPICAL CHARACTERISTICS: +2.7V (Cont.)

At  $T_A = +25^\circ\text{C}$ ,  $+V_{CC} = +2.7\text{V}$ ,  $V_{REF} = +2.5\text{V}$ ,  $f_{\text{SAMPLE}} = 125\text{kHz}$ , and  $f_{\text{CLK}} = 16 \cdot f_{\text{SAMPLE}} = 2\text{MHz}$ , unless otherwise noted.



# TYPICAL CHARACTERISTICS: +2.7V (Cont.)

At  $T_A = +25^\circ\text{C}$ ,  $+V_{CC} = +2.7\text{V}$ ,  $V_{REF} = +2.5\text{V}$ ,  $f_{SAMPLE} = 125\text{kHz}$ , and  $f_{CLK} = 16 \cdot f_{SAMPLE} = 2\text{MHz}$ , unless otherwise noted.





# THEORY OF OPERATION

The ADS7841 is a classic Successive Approximation Register (SAR) ADC. The architecture is based on capacitive redistribution that inherently includes a sample-and-hold function. The converter is fabricated on a 0.6μs CMOS process.

The basic operation of the ADS7841 is shown in Figure 1. The device requires an external reference and an external clock. It operates from a single supply of 2.7V to 5.25V. The external reference can be any voltage between 100mV and +V<sub>CC</sub>. The value of the reference voltage directly sets the input range of the converter. The average reference input current depends on the conversion rate of the ADS7841.

The analog input to the converter is differential and is provided via a four-channel multiplexer. The input can be provided in reference to a voltage on the COM pin (which is generally ground) or differentially by using two of the four input channels (CH0 - CH3). The particular configuration is selectable via the digital interface.

## ANALOG INPUT

Figure 2 shows a block diagram of the input multiplexer on the ADS7841. The differential input of the converter is derived from one of the four inputs in reference to the COM pin or two of the four inputs. Table I and Table II show the relationship between the A2, A1, A0, and SGL/DIF control bits and the configuration of the analog multiplexer. The control bits are provided serially via the DIN pin, see the Digital Interface section of this data sheet for more details.

When the converter enters the hold mode, the voltage difference between the +IN and -IN inputs (as shown in Figure 2) is captured on the internal capacitor array. The voltage on the -IN input is limited between -0.2V and 1.25V, allowing the input to reject small signals that are common to both the +IN and -IN input. The +IN input has a range of -0.2V to +V<sub>CC</sub> + 0.2V.

The input current on the analog inputs depends on the conversion rate of the device. During the sample period, the source must charge the internal sampling capacitor (typically 25pF). After the capacitor has been fully charged, there is no further input current. The rate of charge transfer from the analog source to the converter is a function of conversion rate.

A2	A1	A0	CH0	CH1	CH2	CH3	COM
0	0	1	+IN				-IN
1	0	1		+IN			-IN
0	1	0			+IN		-IN
1	1	0				+IN	-IN

TABLE I. Single-Ended Channel Selection (SGL/DIF HIGH).

A2	A1	A0	CH0	CH1	CH2	CH3	COM
0	0	1	+IN	-IN			
1	0	1	-IN	+IN			
0	1	0			+IN	-IN	
1	1	0			-IN	+IN	

TABLE II. Differential Channel Control (SGL/DIF LOW).

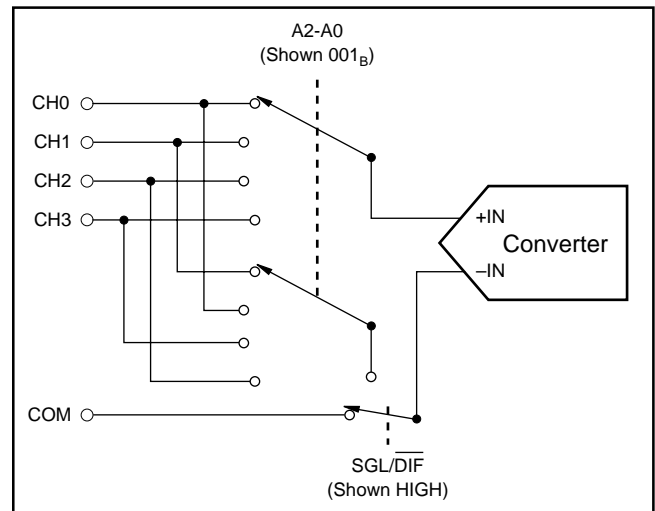


FIGURE 2. Simplified Diagram of the Analog Input.

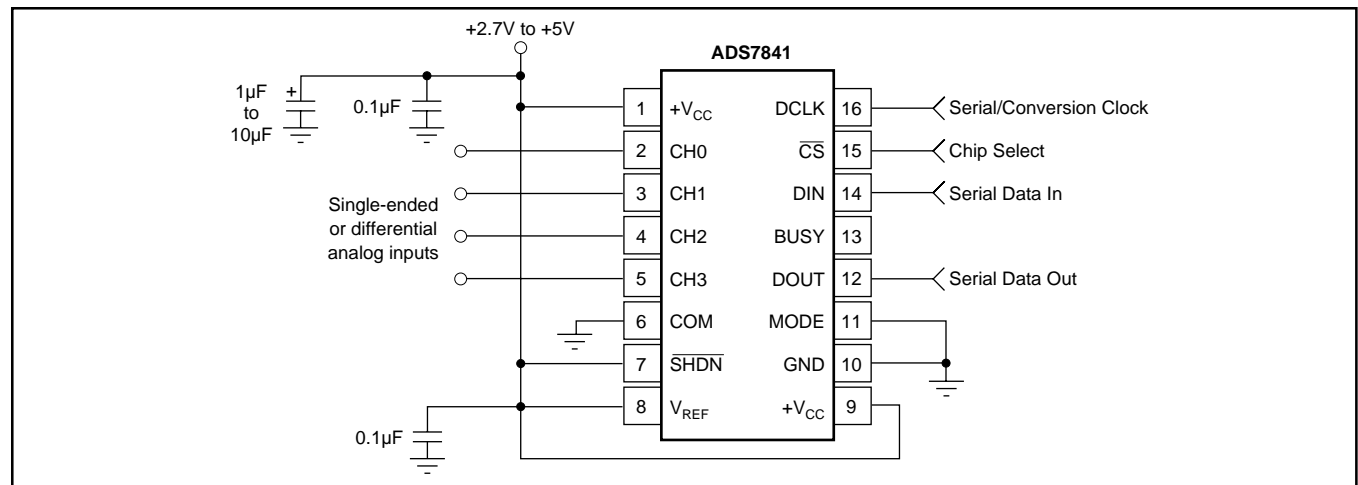


FIGURE 1. Basic Operation of the ADS7841.

## REFERENCE INPUT

The external reference sets the analog input range. The ADS7841 will operate with a reference in the range of 100mV to +V<sub>CC</sub>. Keep in mind that the analog input is the difference between the +IN input and the -IN input, see Figure 2. For example, in the single-ended mode, a 1.25V reference, and with the COM pin grounded, the selected input channel (CH0 - CH3) will properly digitize a signal in the range of 0V to 1.25V. If the COM pin is connected to 0.5V, the input range on the selected channel is 0.5V to 1.75V.

There are several critical items concerning the reference input and its wide voltage range. As the reference voltage is reduced, the analog voltage weight of each digital output code is also reduced. This is often referred to as the LSB (least significant bit) size and is equal to the reference voltage divided by 4096. Any offset or gain error inherent in the ADC will appear to increase, in terms of LSB size, as the reference voltage is reduced. For example, if the offset of a given converter is 2LSBs with a 2.5V reference, then it will typically be 10LSBs with a 0.5V reference. In each case, the actual offset of the device is the same, 1.22mV.

Likewise, the noise or uncertainty of the digitized output will increase with lower LSB size. With a reference voltage of 100mV, the LSB size is 24μV. This level is below the internal noise of the device. As a result, the digital output code will not be stable and vary around a mean value by a number of LSBs. The distribution of output codes will be gaussian and the noise can be reduced by simply averaging consecutive conversion results or applying a digital filter.

With a lower reference voltage, care should be taken to provide a clean layout including adequate bypassing, a clean (low-noise, low-ripple) power supply, a low-noise reference, and a low-noise input signal. Because the LSB size is lower, the converter will also be more sensitive to nearby digital signals and electromagnetic interference.

The voltage into the V<sub>REF</sub> input is not buffered and directly drives the Capacitor Digital-to-Analog Converter (CDAC) portion of the ADS7841. Typically, the input current is 13μA with a 2.5V reference. This value will vary by microamps depending on the result of the conversion. The reference current diminishes directly with both conversion rate and reference voltage. As the current from the reference is drawn on each bit decision, clocking the converter more quickly during a given conversion period will not reduce overall current drain from the reference.

## DIGITAL INTERFACE

Figure 3 shows the typical operation of the ADS7841's digital interface. This diagram assumes that the source of the digital signals is a microcontroller or digital signal processor with a basic serial interface (note that the digital inputs are over-voltage tolerant up to 5.5V, regardless of +V<sub>CC</sub>). Each communication between the processor and the converter consists of eight clock cycles. One complete conversion can be accomplished with three serial communications, for a total of 24 clock cycles on the DCLK input.

The first eight clock cycles are used to provide the control byte via the DIN pin. When the converter has enough information about the following conversion to set the input multiplexer appropriately, it enters the acquisition (sample) mode. After three more clock cycles, the control byte is complete and the converter enters the conversion mode. At this point, the input sample-and-hold goes into the hold mode. The next twelve clock cycles accomplish the actual Analog-to-Digital conversion. A thirteenth clock cycle is needed for the last bit of the conversion result. Three more clock cycles are needed to complete the last byte (DOUT will be LOW). These will be ignored by the converter.

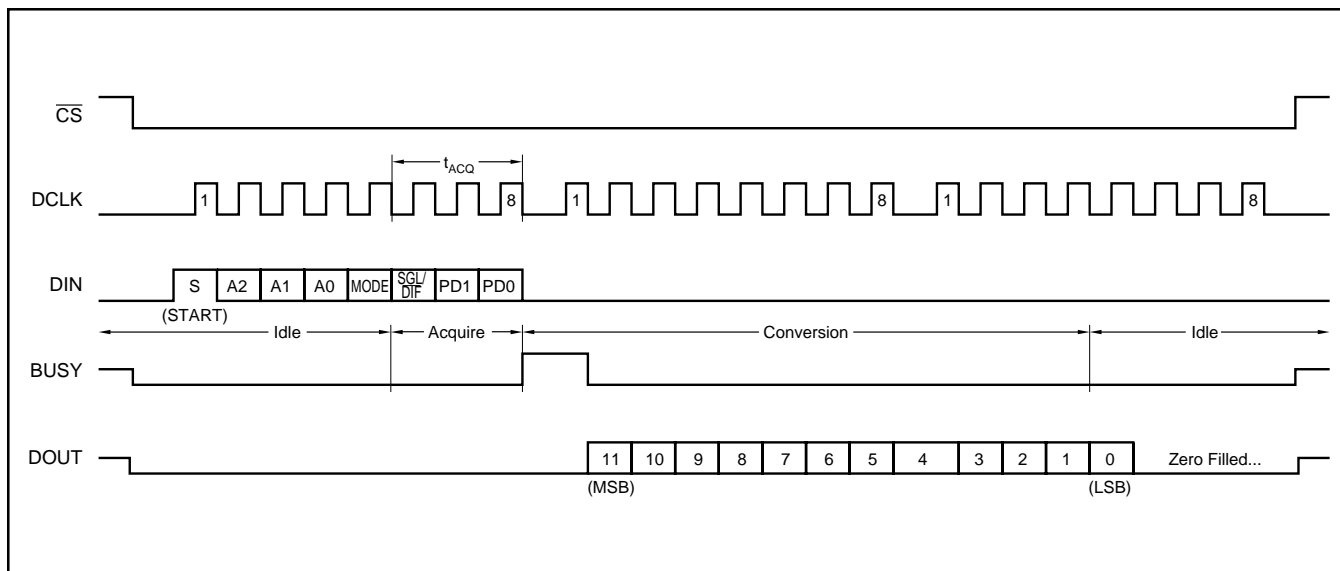


FIGURE 3. Conversion Timing, 24-Clocks per Conversion, 8-Bit Bus Interface. No DCLK delay required with dedicated serial port.

## Control Byte

Also shown in Figure 3 is the placement and order of the control bits within the control byte. Tables III and IV give detailed information about these bits. The first bit, the ‘S’ bit, must always be HIGH and indicates the start of the control byte. The ADS7841 will ignore inputs on the DIN pin until the start bit is detected. The next three bits (A2 - A0) select the active input channel or channels of the input multiplexer (see Tables I and II and Figure 2).

Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)
S	A2	A1	A0	MODE	SGL/DIF	PD1	PD0

TABLE III. Order of the Control Bits in the Control Byte.

BIT	NAME	DESCRIPTION
7	S	Start Bit. Control byte starts with first HIGH bit on DIN. A new control byte can start every 15th clock cycle in 12-bit conversion mode or every 11th clock cycle in 8-bit conversion mode.
6 - 4	A2 - A0	Channel Select Bits. Along with the SGL/DIF bit, these bits control the setting of the multiplexer input, see Tables I and II.
3	MODE	12-Bit/8-Bit Conversion Select Bit. If the MODE pin is HIGH, this bit controls the number of bits for the next conversion: 12-bits (LOW) or 8-bits (HIGH). If the MODE pin is LOW, this bit has no function and the conversion is always 12 bits.
2	SGL/DIF	Single-Ended/Differential Select Bit. Along with bits A2 - A0, this bit controls the setting of the multiplexer input, see Tables I and II.
1 - 0	PD1 - PD0	Power-Down Mode Select Bits. See Table V for details.

TABLE IV. Descriptions of the Control Bits within the Control Byte.

The MODE bit and the MODE pin work together to determine the number of bits for a given conversion. If the MODE pin is LOW, the converter always performs a 12-bit conversion regardless of the state of the MODE bit. If the

MODE pin is HIGH, then the MODE bit determines the number of bits for each conversion, either 12 bits (LOW) or 8 bits (HIGH).

The SGL/DIF bit controls the multiplexer input mode: either single-ended (HIGH) or differential (LOW). In single-ended mode, the selected input channel is referenced to the COM pin. In differential mode, the two selected inputs provide a differential input. See Tables I and II and Figure 2 for more information. The last two bits (PD1 - PD0) select the power-down mode, as shown in Table V. If both inputs are HIGH, the device is always powered up. If both inputs are LOW, the device enters a power-down mode between conversions. When a new conversion is initiated, the device will resume normal operation instantly—no delay is needed to allow the device to power up and the very first conversion will be valid.

## 16-Clocks per Conversion

The control bits for conversion n+1 can be overlapped with conversion ‘n’ to allow for a conversion every 16 clock cycles, as shown in Figure 4. This figure also shows possible serial communication occurring with other serial peripherals between each byte transfer between the processor and the converter. This is possible provided that each conversion completes within 1.6ms of starting. Otherwise, the signal that has been captured on the input sample-and-hold may droop enough to affect the conversion result. In addition, the ADS7841 is fully powered while other serial communications are taking place.

PD1	PD0	Description
0	0	Power-down between conversions. When each conversion is finished, the converter enters a low power mode. At the start of the next conversion, the device instantly powers up to full power. There is no need for additional delays to assure full operation and the very first conversion is valid.
0	1	Reserved for Future Use
1	0	Reserved for Future Use
1	1	No power-down between conversions, device always powered.

TABLE V. Power-Down Selection.

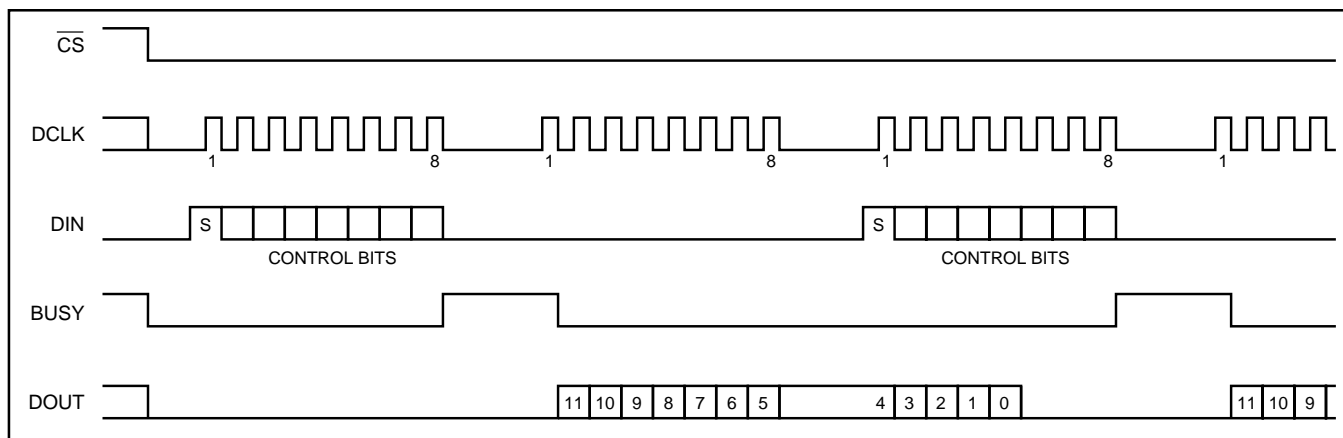


FIGURE 4. Conversion Timing, 16-Clocks per Conversion, 8-bit Bus Interface. No DCLK delay required with dedicated serial port.

## Digital Timing

Figure 5 and Tables VI and VII provide detailed timing for the digital interface of the ADS7841.

### 15-Clocks per Conversion

Figure 6 provides the fastest way to clock the ADS7841. This method will not work with the serial interface of most

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
$t_{ACQ}$	Acquisition Time	1.5			$\mu$ s
$t_{DS}$	DIN Valid Prior to DCLK Rising	100			ns
$t_{DH}$	DIN Hold After DCLK HIGH	10			ns
$t_{DO}$	DCLK Falling to DOUT Valid			200	ns
$t_{DV}$	$\overline{CS}$ Falling to DOUT Enabled			200	ns
$t_{TR}$	$\overline{CS}$ Rising to DOUT Disabled			200	ns
$t_{CSS}$	$\overline{CS}$ Falling to First DCLK Rising	100			ns
$t_{CSH}$	$\overline{CS}$ Rising to DCLK Ignored	0			ns
$t_{CH}$	DCLK HIGH	200			ns
$t_{CL}$	DCLK LOW	200			ns
$t_{BD}$	DCLK Falling to BUSY Rising			200	ns
$t_{BDV}$	$\overline{CS}$ Falling to BUSY Enabled			200	ns
$t_{BTR}$	$\overline{CS}$ Rising to BUSY Disabled			200	ns

TABLE VI. Timing Specifications ( $+V_{CC} = +2.7V$  to  $3.6V$ ,  $T_A = -40^\circ C$  to  $+85^\circ C$ ,  $C_{LOAD} = 50pF$ ).

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
$t_{ACQ}$	Acquisition Time	900			ns
$t_{DS}$	DIN Valid Prior to DCLK Rising	50			ns
$t_{DH}$	DIN Hold After DCLK HIGH	10			ns
$t_{DO}$	DCLK Falling to DOUT Valid			100	ns
$t_{DV}$	$\overline{CS}$ Falling to DOUT Enabled			70	ns
$t_{TR}$	$\overline{CS}$ Rising to DOUT Disabled			70	ns
$t_{CSS}$	$\overline{CS}$ Falling to First DCLK Rising	50			ns
$t_{CSH}$	$\overline{CS}$ Rising to DCLK Ignored	0			ns
$t_{CH}$	DCLK HIGH	150			ns
$t_{CL}$	DCLK LOW	150			ns
$t_{BD}$	DCLK Falling to BUSY Rising			100	ns
$t_{BDV}$	$\overline{CS}$ Falling to BUSY Enabled			70	ns
$t_{BTR}$	$\overline{CS}$ Rising to BUSY Disabled			70	ns

TABLE VII. Timing Specifications ( $+V_{CC} = +4.75V$  to  $+5.25V$ ,  $T_A = -40^\circ C$  to  $+85^\circ C$ ,  $C_{LOAD} = 50pF$ ).

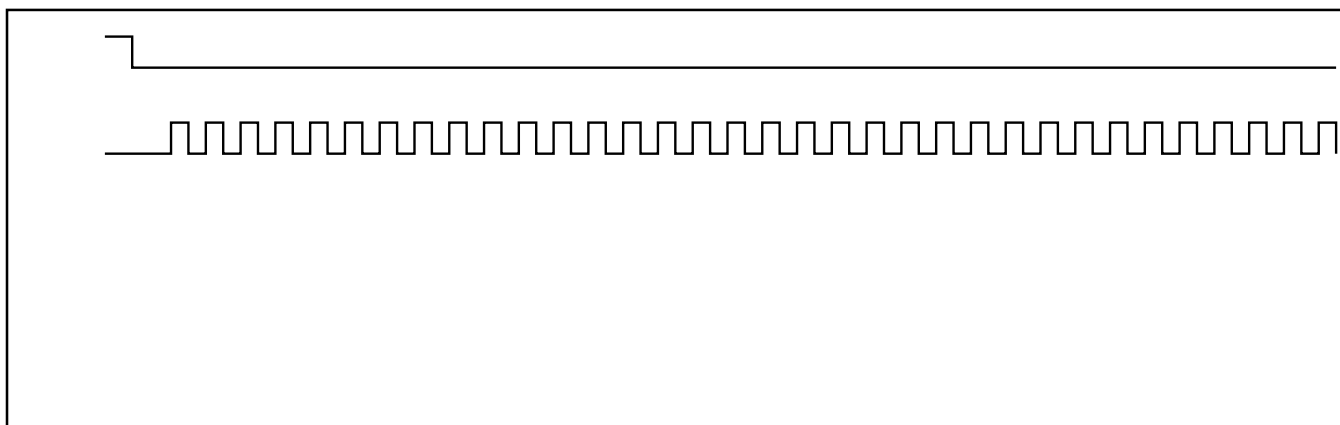
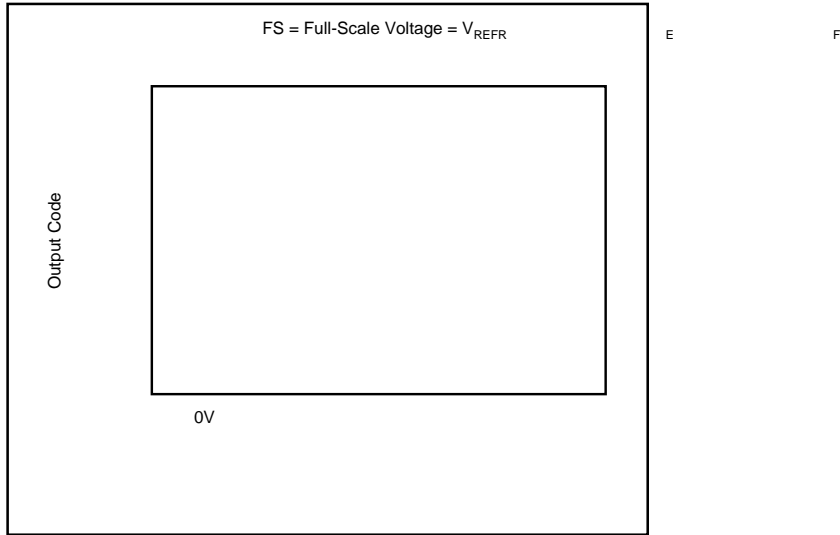


FIGURE 6. Maximum Conversion Rate, 15-Clocks per Conversion.

## Data Format

The ADS7841 output data is in straight binary format, as shown in Figure 7. This figure shows the ideal output code for the given input voltage and does not include the effects of offset, gain, or noise.





**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
ADS7841E	ACTIVE	SSOP/QSOP	DBQ	16	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841E/2K5	ACTIVE	SSOP/QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841E/2K5G4	ACTIVE	SSOP/QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841EB	ACTIVE	SSOP/QSOP	DBQ	16	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841EB/2K5	ACTIVE	SSOP/QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841EB/2K5G4	ACTIVE	SSOP/QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841EBG4	ACTIVE	SSOP/QSOP	DBQ	16	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841EG4	ACTIVE	SSOP/QSOP	DBQ	16	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841ES	ACTIVE	SSOP/QSOP	DBQ	16	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841ES/2K5	ACTIVE	SSOP/QSOP	DBQ	16		TBD	Call TI	Call TI
ADS7841ES/2K5G4	ACTIVE	SSOP/QSOP	DBQ	16		TBD	Call TI	Call TI
ADS7841ESG4	ACTIVE	SSOP/QSOP	DBQ	16	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7841P	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
ADS7841PB	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
ADS7841PBG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
ADS7841PG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS7841E/2K5	SSOP/QSOP	DBQ	16	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ADS7841EB/2K5	SSOP/QSOP	DBQ	16	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS7841E/2K5	SSOP/QSOP	DBQ	16	2500	346.0	346.0	29.0
ADS7841EB/2K5	SSOP/QSOP	DBQ	16	2500	346.0	346.0	29.0

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

### Products

Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
RF/IF and ZigBee® Solutions	<a href="http://www.ti.com/lprf">www.ti.com/lprf</a>

### Applications

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
Wireless	<a href="http://www.ti.com/wireless">www.ti.com/wireless</a>

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2008, Texas Instruments Incorporated